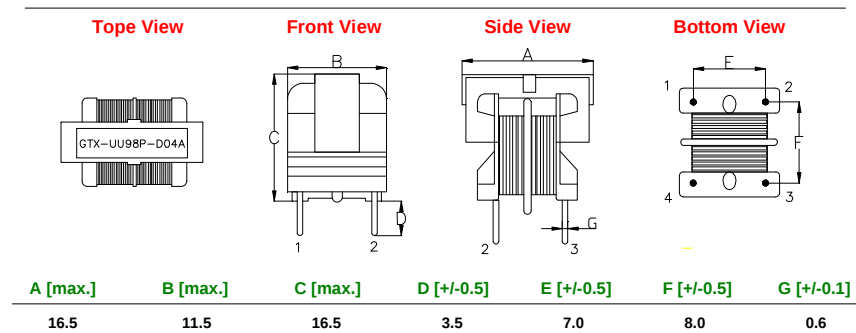
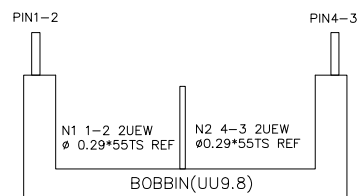


Product Series Code	GTX	Brand	GOTREND
File Version	GTX-UU98P-D04A-V1R0	Editor	Lucifer
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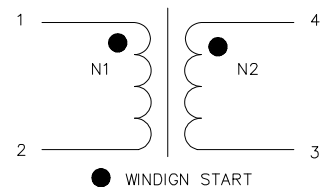
DIMENSION : [mm]



WINDING CONSTRUCTION :



SCHEMATIC :



NO	WINDING	TERMINAL	WIRE	TURNS
1	N1	1----2	2UEW - 0.29 mm	55.0 Ts
2	N2	4----3	2UEW - 0.29 mm	55.0 Ts
MATERIAL				
DESCRIPTION	MATERIAL	MANUFACTURER		UL NO.
CORE	UU9.8	CHENGDUHENGLIMAGNETIC MATERIALSCO.LTD.		
BOBBIN	PHENOLIC UU9.8	CHANG CHUN PLASTICS CO.,LTD OR EQU.		E59481
WIRE	2UEW	EASEBOND ELECTRICAL MATERIAL DONGGUAN CO. LTD.		E173779
TAPE	POLYESTER FILM	CHANG SHU LIANG YI TAPE INDUSTRY CO LTD		E246820
VARNISH	98CA02489	ADVANCED INK & COATINGS LTD		E200154
ELEC. SPEC				
L (1 - 2) (4 - 3) (1KHz / 0.25V)	HI-POT N1-N2 (50Hz / 3mA / 1sec)	HI-POT N1/N2-CORE (50Hz / 3mA / 1sec)	INSULATION RESISTANCE N1-N2 ; N1/N2-CORE	
7.6 mH Min.	AC 1.0 KV	AC 1.0 KV	DC 500V / 100M Ohm Min.	
TEST CONTITION				
1. LCR meter CH1061				
2. Operating Temperature : -40℃ ~ + 85℃.				

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Reliability Test Result :																			
NO	ITEM	TEST CONDITIONS	REMARKS																
1	Thermal Shock (Temperature Cycle) 溫度循環試驗	Temperature: -40 ° C / +85 ° C kept stabilized for 30 minutes each Cycle: 100 Cycles	There must be no deformation or change in dimension. Inductance must not change more than the stated tolerance.																
2	Humidity Resistance 耐濕試驗	Humidity: 90%~ 95% RH Temperature: 40± 2 ° C Test Time: 500± 12 Hours	There must be no case deformation or change in dimensions. Inductance must as specification stated.																
3	High Temperature 耐熱試驗	Temperature: 85± 2 ° C Humidity: 20% Test Time: 500± 12 Hours	There must be no case deformation or change in dimensions. Inductance must as specification stated.																
4	Low Temperature 耐寒試驗	Temperature: -40 ± 2 ° C Test Time: 500± 12 Hours	There must be no case deformation or change in dimensions. Inductance must as specification stated.																
5	Temperature and Humidity Cycle 溫/濕度循環試驗	<table border="1"> <thead> <tr> <th>Step</th><th>Temp</th><th>Humidity</th><th>Time</th></tr> </thead> <tbody> <tr> <td>1</td><td>25± 2 ° C</td><td>95~100%RH</td><td>3.0Hr</td></tr> <tr> <td>2</td><td>55± 2 ° C</td><td>95~96%RH</td><td>9.5Hr</td></tr> <tr> <td>3</td><td>25± 2 ° C</td><td>95~100%RH</td><td>9.5Hr</td></tr> </tbody> </table>	Step	Temp	Humidity	Time	1	25± 2 ° C	95~100%RH	3.0Hr	2	55± 2 ° C	95~96%RH	9.5Hr	3	25± 2 ° C	95~100%RH	9.5Hr	There must be no case deformation or change in dimensions. Inductance must as specification stated.
Step	Temp	Humidity	Time																
1	25± 2 ° C	95~100%RH	3.0Hr																
2	55± 2 ° C	95~96%RH	9.5Hr																
3	25± 2 ° C	95~100%RH	9.5Hr																
6	Vibration 振動性試驗	Frequency: 10Hz~50Hz Amplitude: 1.5mm Direction: X,Y,Z Time: 2 Hours each	Solder inductors on the test PCB. After vibration, there must be no deformation or change in dimension. Inductance must not change more than the stated tolerance.																
7	IR Reflow Soldering 焊錫性試驗	Solder: H63A(eutectic solder) Solder Temp.: 232± 5 ° C Time: 6 minutes Cycles: x 1	Inductance shall be within ± 20% of the initial value. DCR value shall be within ± 20% of the initial value.																
8	Soldering Heat Resistance 耐熱 焊性試驗	Preheat: 120 ~ 150 ° C (60 sec) Solder: H63A(eutectic solder) Solder Temp.: 260 ± 5 ° C Flux: Rosin Dip time: 10± 1 seconds	The chip must have no cracks. More than 75% of the terminal electrode must be covered with solder. For 96.5 Sn / 3.5 Ag Solder Past: > 217 ° C / 90 Seconds. For 63.0 Sn / 37 Pb Solder Past: > 183 ° C / 120 Seconds.																

BOX Package: cm

